

1612507-3 ✓ ACTIVE

DDR SODIMM, DDR2 SO DIMM

TE Internal #: 1612507-3

SO DIMM Sockets, Double Data Rate (DDR), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 200 Position, DDR SODIMM

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR2 SO DIMM Sockets



DRAM Type: **Double Data Rate (DDR)**

Stack Height: **5.2 mm [.205 in]**

Module Orientation: **Right Angle**

Connector System: **Cable-to-Board**

Number of Positions: **200**

[All DDR2 SO DIMM Sockets \(30\)](#)

Features

Product Type Features

DRAM Type	Double Data Rate (DDR)
Connector System	Cable-to-Board
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Bays	2
Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	200

Electrical Characteristics

DRAM Voltage	2.5 V
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Signal Characteristics



SGRAM Voltage	2.5 V
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Body Features

Ejector Location	Both Ends
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Retention Post Material	Copper Alloy
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Latch Material	Stainless Steel
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Latch Plating Material	Tin
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Module Key Type	SGRAM
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Ejector Type	Locking
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Connector Profile	Standard
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Contact Features

Memory Socket Type	Memory Card
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PCB Contact Termination Area Plating Material	Gold Flash
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Contact Base Material	Copper Alloy
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Contact Mating Area Plating Material	Gold Flash
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Contact Current Rating (Max)	.5 A
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Termination Features

Insertion Style	Cam-In
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Mechanical Attachment

Mating Alignment Type	Standard Keying
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PCB Mounting Style	Surface Mount
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PCB Mount Retention	With
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PCB Mount Retention Type	Solder Tail
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Connector Mounting Type	Board Mount
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Housing Features

Housing Material	High Temperature Thermoplastic
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Housing Color	Black
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Centerline (Pitch)	.6 mm [.024 in]
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Dimensions

Stack Height	5.2 mm [.205 in]
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Row-to-Row Spacing	6.2 mm [.244 in]
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Usage Conditions

Operating Temperature Range	-55 – 85 °C [-67 – 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	16
Packaging Method	Hard Tray

Other

Socket Connector Comment	Solder peg plating, tin.
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 245°C

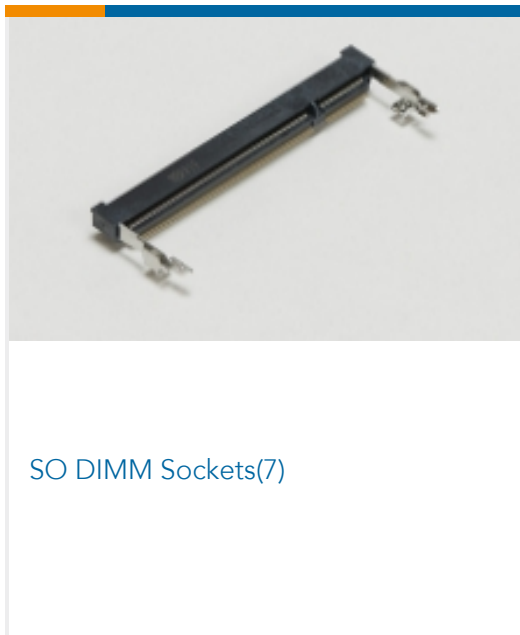
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | **DDR SODIMM**



Also in the Series | **DDR2 SO DIMM**



Customers Also Bought





TE Part #4-794682-2
12P MICRO MNL ASSY,VRT,THRU,LF



TE Part #5767054-2
MICT,RECPT,76,ASSY,PDNI



TE Part #1513472-5
UAM Assembly 360mm cable



TE Part #50845-2
TERMINAL,PIDG PTFE R 12-10 10



TE Part #4-794682-8
18P MICRO MNL ASSY,VRT,THRU,L

Documents

Product Drawings

HARD TRAY ASS'Y DDR SODIMM SOC

English

CAD Files

Customer View Model

[ENG_CVM_CVM_1612507-3_D1.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_1612507-3_D1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1612507-3_D1.3d_stp.zip](#)

English

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Product Specifications

Application Specification

English

Product Environmental Compliance

TE Material Declaration

English